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Date: February 11, 2003

Christine M. Spivey

PATENT
36856.593

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Takeshi NAKAO et al.	Art Unit: 2834
Serial No.: 10/043,204	Examiner: Unknown
Filed: January 14, 2002	
Title: SURFACE ACOUSTIC WAVE DEVICE AND FREQUENCY ADJUSTMENT METHOD OF THE SAME	

INFORMATION DISCLOSURE STATEMENT

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

Dear Sir:

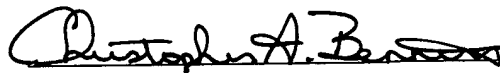
Pursuant to 37 C.F.R. § 1.56, submitted herewith are copies of seven (7) references cited in the enclosed examination report issued in a corresponding Japanese patent application. For the Examiner's convenience, we have enclosed an English translation of the Japanese examination report from the corresponding Japanese Patent Application and a completed Form PTO-1449. The statement is not a representation that all of the information cited is necessarily effective as prior art against the application.

I hereby state that each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than 3 months prior to the filing of this statement, and that this is the first citation of these prior art references by a foreign patent office in a counterpart foreign patent application. Accordingly, no fee is necessary for the filing of this statement. Should the Commissioner determine otherwise, the Commissioner is authorized to charge Deposit Account No. 50-1353 for any fee shortages, including the petition fee under 37 C.F.R. § 1.17(p).

Applicants respectfully request that the disclosed references be made of record in the subject application.

Respectfully submitted,

Date: February 11, 2003

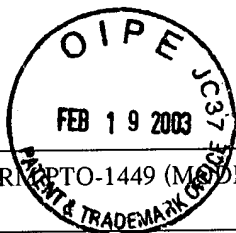


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FOR PTO-1449 (MODIFIED)				ATTY. DOCKET NO. 36856.593		SERIAL NO.: 10/043,204	
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANTS INFORMATION DISCLOSURE STATEMENT (USE SEVERAL SHEETS IF NECESSARY)				APPLICANT(S): Takeshi NAKAO et al.			
Sheet	1	of	1	FILING DATE: January 14, 2002		GROUP: 2834	
U.S PATENT DOCUMENTS							
Examiner Initial	Document Number	Date	Name	Class	Filing Date Subclass if appropriate		
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
FOREIGN PATENT DOCUMENTS							
	Document Number	Date	Country	Class	Filing Date Subclass if appropriate		
	AG 4-199906 A (With English Abstract)	7/1992	Japan				
	AH 61-020410 A (With English Abstract)	1/1986	Japan				
	AI 1-240007 A (With English Abstract)	9/1989	Japan				
	AJ 56-103513 A (With English Abstract)	8/1981	Japan				
	AK 6-350390 A (With English Abstract)	12/1994	Japan				
	AL 10-190402 A (With English Abstract)	7/1998	Japan				
	AM 2000-315928 A (With English Abstract)	11/2000	Japan				
	AN						
	AO						
OTHER ART (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)							
	AP						
	AR						
	AS						
	AT						
EXAMINER				DATE CONSIDERED			

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

File No. DP010023

Dispatch No. 004615

Date of Dispatch: January 14, 2003

1/2

[Stamp: Miyazaki, 1/15/03, Mototsugu]

NOTIFICATION OF REASONS FOR REJECTION

Patent Application No.:	Patent Application No. 2001-034984
Draft Date:	January 7, 2003
Patent Office Examiner:	Minoru Shimizu 3248 5W00
Agent of Patent Applicant:	Chikara Miyazaki
Applicable Sections:	Section 29 (2)

The present application should be rejected for the following reasons. If you have an opinion concerning this, please submit a statement of opinion within 60 days of the date of dispatch of this notification.

Reasons

The inventions claimed in the following claims of the present application are inventions that could easily have been invented prior to the filing of the application by a person having an ordinary knowledge of the technical field to which the inventions belong on the basis of inventions described in the following publication, which was disseminated in Japan or in foreign countries prior to the filing of the application, or inventions that have become accessible to the public through electric communication lines. Thus, in accordance with the provisions of Section 29 (2) of the Patent Law, these inventions cannot be patented.

Note

Cited Example 1: Japanese Patent Application Kokai No. 2000-315928

Claims: 1 through 6

Cited Example: 1

Remarks:

When the inventions described in the Claims [section], in lines 14 through 22 in the left column of page 4, and in Figures 1 through 6 of Cited Example 1 are compared with the inventions according to Claims 1 through 6 of the present application, no particular difference exists, except that the inventions according to Claims 1 through 6 of the present application are constructed such that "the bonding wires are arranged so as not to pass over the interdigital transducers or the reflectors of the above-mentioned surface acoustic wave element," whereas there is no clear description of concrete conditions regarding the bonding wire arrangement in the inventions described in Cited Example 1.

The above-mentioned difference is now judged from this comparison. It is clear from common sense that when [an object] is irradiated with a beam or the like, [the object] should preferably be placed so that no obstacles are present in the beam path. In the technical field of surface acoustic wave devices, furthermore, a surface acoustic wave device having a construction such that "the bonding wires are arranged so as not to pass over the interdigital transducers or the

[Stamp: 1/16/03, Otaru]

reflectors of the above-mentioned surface acoustic wave element” is also universally known (for example, see Figure 2 of Japanese Patent Application Kokai No. H10-190402, Figure 7 of Japanese Patent Application Kokai No. H6-350390, and Figures 1 and 2 of Japanese Patent Application Kokai No. S56-103513). Accordingly, for the purpose of avoiding the interference in the path of the ion particles emitted from the ion beam, a person skilled in the art could appropriately devise the arrangement of the bonding wires in the invention described in Cited Example 1 as well such that “the bonding wires are arranged so as not to pass over the interdigital transducers or the reflectors of the above-mentioned surface acoustic wave element.”

Please direct any inquiries regarding the content of this Notification of Reasons for Rejection, or any requests for an interview to:

Patent Examination Department 4, Examiner Minoru Shimizu, Assistant Examiner Hiroyuki Inoue
TEL: 03 (3581) 1101, extension 6441
FAX: 03 (3501) 0699

Record of Results of Survey of Prior Art References

- Field surveyed: IPC 7th Edition H 03 H 9/145, 25, 64
- Prior Art References: Japanese Patent Application Kokai No. H1-240007, Japanese Patent Application Kokai No. S61-20410, Japanese Patent Application Kokai No. H4-199906

整理番号 DP010023

発送番号 004615

発送日 平成15年 1月14日 1 / 2



3/15

拒絶理由通知書

特許出願の番号	特願2001-034984
起案日	平成15年 1月 7日
特許庁審査官	清水 稔 3248 5W00
特許出願人代理人	宮▼崎▲ 主税 様
適用条文	第29条第2項

この出願は、次の理由によって拒絶をすべきものである。これについて意見があれば、この通知書の発送の日から60日以内に意見書を提出して下さい。

理 由

この出願の下記の請求項に係る発明は、その出願前日本国内又は外国において頒布された下記の記事に記載された発明又は電気通信回線を通じて公衆に利用可能となった発明に基いて、その出願前にその発明の属する技術の分野における通常の知識を有する者が容易に発明をすることができたものであるから、特許法第29条第2項の規定により特許を受けることができない。

記

引例1：特開2000-315928号公報

請求項：1～6

引例：1

備考：

引例1の特許請求の範囲、第4頁目左欄第14～22行目及び第1～6図に記載された発明と本願の請求項1～6に係る発明とを比較すると、本願の請求項1～6に係る発明は、「ボンディングワイヤが、前記弾性表面波素子のインターデジタルトランスデューサーの上方及び反射器の上方の領域の双方を経由しないように配置されている」構成であるのに対し、引例1に記載された発明には、ボンディングワイヤの配置について、具体的な条件が明記されていない点で相違する以外は格別の相違点を有しない。

そこで、上記相違点について対比判断すると、ビーム等を照射する際に、その経路上に障害物が存在しないように配置する方が望ましいことは、常識的に明らかなことであって、しかも、弾性表面波装置の技術分野において、「ボンディングワイヤが、前記弾性表面波素子のインターデジタルトランスデューサーの上方



及び反射器の上方の領域の双方を経由しないように配置されている」構成を有する弾性表面波装置も、周知（例：特開平10-190402号公報第2図、特開平6-350390号公報第7図、特開昭56-103513号公報第1、2図参照）であるから、引例1に記載された発明においても、イオンビームから照射されるイオン粒子の経路を妨げないようにする目的で、ボンディングワイヤの配置を、「ボンディングワイヤが、前記弾性表面波素子のインターデジタルトランスデューサーの上方及び反射器の上方の領域の双方を経由しないように配置されている」構成とすることは、当業者が適宜なしうることである。

この拒絶理由通知の内容に関するお問い合わせ、または面接のご希望がございましたら下記までご連絡下さい。

特許審査第4部 審査官 清水 稔 審査官補 井上 弘亘
TEL. 03 (3581) 1101 内線 6441
FAX. 03 (3501) 0699

先行技術文献調査結果の記録

・調査した分野 IPC第7版 H03H 9/145、25、64

・先行技術文献 特開平1-240007号公報、特開昭61-20410号公報、特開平4-199906号公報